

element may be substituted for two or more elements in a claim. Although elements may be described above as acting in certain combinations and even initially claimed as such, it is to be expressly understood that one or more elements from a claimed combination can in some cases be excised from the combination and that the claimed

5 combination may be directed to a subcombination or variation of a subcombination.

Insubstantial changes from the claimed subject matter as viewed by a person with ordinary skill in the art, now known or later devised, are expressly contemplated as being equivalently within the scope of the claims. Therefore, obvious substitutions now

10 or later known to one with ordinary skill in the art are defined to be within the scope of the defined elements.

The claims are thus to be understood to include what is specifically illustrated and described above, what is conceptually equivalent, what can be obviously substituted

15 and also what essentially incorporates the essential idea of the invention.

Claims

I claim:

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1. A method for interconnecting a plurality of electronic assemblies to form a cornerbond assembly comprised of:

25 providing a first electronic assembly with a first surface, said first surface including a conductive pattern thereon, said conductive pattern including a first terminal edge,

providing a second electronic assembly with a second surface, said second surface including a conductive pattern thereon, said conductive pattern including a second terminal edge,

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orienting said first electronic assembly with respect to said second electronic assembly whereby said first surface is angularly disposed to said second surface and said first terminal edge and said second terminal edge are substantially registered to form a junction,

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Fixedly applying at least one conductive ball to said junction whereby said first conductive pattern is electrically interconnected to said second conductive pattern.

10 2. The method of Claim 1 wherein said first electronic assembly includes a three dimensional, multi-layer electronic module and said second electronic assembly includes a printed circuit board.

3. The method of Claim 1 wherein said first surface and said second surface are angularly disposed at an angle of about 90 degrees.

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4. The method of Claim 1 wherein said first surface and said second surface are angularly disposed at an angle greater than 90 degrees.

20 5. The method of Claim 1 wherein said first surface and said second surface are angularly disposed at an angle less than 90 degrees.

6. The method of Claim 1 further comprising the step of encapsulating said junction after said at least one conductive ball has been fixedly applied

25 7. A cornerbond assembly comprised of:

a first electronic assembly with a first surface, said first surface including a conductive pattern thereon, said conductive pattern including a first terminal edge,

30 a second electronic assembly with a second surface, said second surface including a conductive pattern thereon, said conductive pattern including a second terminal edge,

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said first electronic assembly and said second electronic assembly oriented whereby said first surface is angularly disposed to said second surface and said first terminal edge and said second terminal edge are substantially registered to form a junction,

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at least one conductive ball fixedly applied to said junction whereby said first conductive pattern is electrically interconnected to said second conductive pattern.

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8. The cornerbond assembly of Claim 7 wherein said first electronic assembly is a three dimensional, multi-layer electronic module and said second electronic assembly is a printed circuit board.

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9. The cornerbond assembly of Claim 7 wherein said first surface and said second surface are angularly disposed at an angle of about 90 degrees.

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10. The cornerbond assembly of Claim 7 wherein said first surface and said second surface are angularly disposed at an angle greater than 90 degrees.

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11. The cornerbond assembly of Claim 7 wherein said first surface and said second surface are angularly disposed at an angle less than 90 degrees.

12. The cornerbond assembly of Claim 7 wherein said at least one conductive ball is encapsulated with an encapsulant.